

HH-D01 NearLink Development Board Specification V1.2

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1 Overview

Model:HH-D01

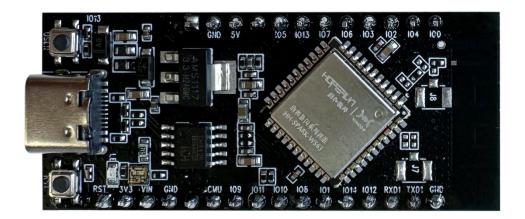


Figure 1-1 HH-D01 NearLink Development Board

The HH-D01 adopts the HiSilicon NearLink WS63 solution, offering support for the 802.11b/g/n/ax wireless communication protocols, and is also compatible with the BLE5.3 protocol.

- It features BLE Mesh and BLE gateway capabilities.
- Supports the SLE1.0 protocol and SLE gateway functionality.
- Enables IoT scenario development based on the lightweight Oniro system.

This makes it an ideal choice in the field of IoT smart terminals.

HH-D01 has the following features:

- Stable and reliable communication capabilities
- Supports reliable communication algorithms such as TPC, automatic rate, and weak interference immunity in complex environments
- Flexible networking capabilities
- ♦ Support BLE Mesh networking



Supports three networking methods: Wi-Fi, BLE or SLE

Complete network support

- ♦ Support IPv4/IPv6 network functions
- ♦ Support DHCPv4/DHCPv6 Client/Server
- ♦ Support DNS Client function
- Support mDNS function
- ♦ Support CoAP/MQTT/HTTP/JSON basic components

Powerful security engine

- Hardware implementation of AES128/256 encryption and decryption algorithm
- Hardware implementation of HASH-SHA256 and HMAC_SHA256 algorithms
- ♦ Hardware implementation of RSA and ECC signature verification algorithms
- Hardware implements true random number generation, meeting FIPS140-2 random testing standards
- ♦ Hardware supports TLS/DTLS acceleration
- ♦ Hardware supports national secret algorithms SM2, SM3, SM4
- ♦ Internally integrated EFUSE, supporting secure storage, secure boot, and hardware ID
- ♦ Internally integrated MPU features support memory isolation features

Open operating system

- Open operating system Oniro provides an open, efficient and secure system development and operating environment
- Rich low power consumption, small memory, high stability, high real-time mechanism
- Flexible protocol support and expansion capabilities



- Secondary development interface
- Multi-level development interface: operating system adaptation interface and system diagnostic interface, link layer interface, network layer interface



1.1 Main specifications

Table 1-1 Main specifications of HH-D01 NearLink development board

Module	Specification description
	● 1×1 2.4GHz frequency band (ch1 ~ ch14)
	PHY supports IEEE 802.11b/g/n/ax MAC supports IEEE 802.11d/e/i/k/v/w
	• Support 802.11n 20MHz/40MHz bandwidth, support 802.11ax 20MHz
	bandwidth
	• Supported maximum rate: 150Mbps@HT40 MCS7, 114.7Mbps@HE20
	MCS9
Wi-Fi	Built-in PA and LNA, integrated TX/RX Switch, Balun, etc.
VVI-11	• Supports STA and AP forms. When used as an AP, it supports up to 6 STAs.
	Support A-MPDU, A-MSDU
	Support Block-ACK
	Support QoS to meet different business service quality requirements
	Support WPA/WPA2/WPA3 personal, WPS2.0
	Supports RF self-calibration scheme
	Supports STBC and LDPC
	Bluetooth Low Energy (BLE)
	• Support BLE 4.0/4.1/4.2/5.0/5.1/5.2
	Supports 125Kbps, 500Kbps, 1Mbps, 2Mbps rates
Bluetooth	Support multicast
	Support Class 1
	Support high power 20dBm
	Support BLE Mesh, support BLE gateway
	Sparklink Low Energy (SLE)
	Support SLE 1.0
NearLink	Support SLE 1MHz/2MHz/4MHz, maximum air interface rate 12Mbps
	Supports Polar channel coding
	Support SLE gateway
	High-performance 32bit microprocessor, maximum operating frequency
CPU	240MHz
subsystem	Embedded SRAM 606KB, ROM 300KB
	Embedded 4MB Flash
	1 SPI interface, 1 QSPI interface, 2 I2C interfaces, 1 I2S interface, 3 UART 10 CPI2 in face, 2 I2C interfaces, 1 I2S interface, 3 UART 10 CPI2 in face, 2 I2C interfaces, 1 I2S interface, 3 UART
Peripheral	interfaces, 19 GPIO interfaces, 6 ADC inputs, 8 PWM (Note: the above
interface	interfaces are implemented through multiplexing)
	External crystal clock frequency 24MHz, 40MHz Mi Figure do STA, Soft AB and aniffor models.
	Wi-Fi mode STA, Soft-AP and sniffer modes Society and spices MAPS (MAPA (MAPA 2 (MAPA 2)) William and spices MAPS (MAPA 2)
Soft-vers	Security mechanism WPS / WEP / WPA / WPA2 / WPA3 From the LART Developed
Software	Encryption type UART Download Software Download Software
	Software Development SDK Network protocol IDVA TCD/IDDR/HTTD/FTD/MOTT
044	Network protocol IPv4, TCP/UDP/HTTP/FTP/MQTT Complexed to a complete to a co
Other	Supply voltage input: typical 5V



information ● Operating temperature: -40°C ~ +85°C

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2 Hardware description

2.1 Function layout

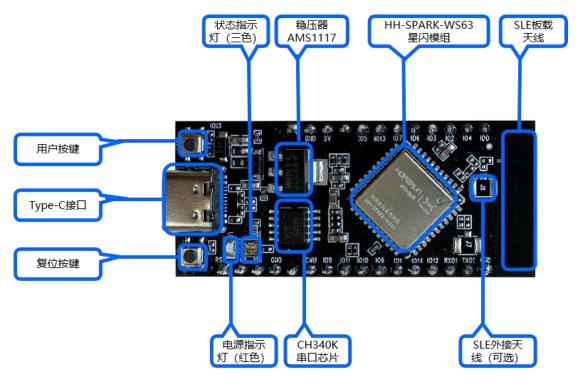


Figure 2-1 HH-D01 NearLink Development Board Functions

1) User buttons

USER is a user-defined button, and switch S2 reports the "pressed/released" status to WS63E through the GPIO13 pin. Functionality is customized by software.

2) Type-C interface

It can power the motherboard and the entire package, or connect to a computer for serial port debugging and system programming.

3) reset button

RST is the reset button, which can reset the motherboard.

4) Power indicator light (red)



It is used to indicate the power status. The power indicator light turns on after normal power-on.

5) Status indicator light (three colors)

Used to indicate the use of related IO port status, and the user controls it through PWM.

6) Voltage regulator AMS1117

Used to convert the 5V power supply of the serial port into the 3.3V power supply of the chip.

7) CH340K USB to serial port chip

When using the serial port function, the driver for the chip needs to be installed on the PC.

8) HH-SPARK WS63E module

Highly integrated with 2.4G Wi-Fi 6, BLE and SLE, it features high-speed transmission, low latency, high performance, low power consumption, Type-C USB interface and rich pin functions.

9) SLE onboard antenna

Used to enhance SLE/BLE/Wi-Fi signals

10) SLE external antenna (optional)

It is used to enhance the SLE/BLE/Wi-Fi signal, using the 1st generation IPEX interface. It can be used in special scenarios that require a strong signal, which can be achieved by replacing the welding resistor.



2.2 Pin definition



Figure 2-2 HH-D01 NearLink development board interface

Table 2-1 HH-D01 NearLink development board interface

	Table 2-1 HH-D01 NearLink development board interface					
seri	name	type	Function			
al						
num						
ber						
1	NC		Not connected			
2	GND	PWR	power ground			
3	5V	PWR	Power supply, 5V			
4	NC		Not connected			
5	GPIO05	Ю	GPIO05, SSI_DATA, SPI1_IO2, UART2_CTS, PWM5,DFT_JTAG_TCK			
6	GPIO13	Ю	GPIO13, UART_CTS, DFT_JTAG_TDO, JTAG_TMS			
7	GPIO07	0	GPIO07, PWM7, UART2_RXD, SPI0_SCK, I2S_MCLK, ADC0			
8	GPIO06	0	GPIO06, PWM6, UART2_RTS, SPI1_SCK, DFT_JTAG_TDI, SPI0_OUT			
9	GPIO03	Ю	GPIO03, PWM3, SPI1_IO1			
10	GPIO02	Ю	GPIO02, PWM2, SPI_IO3			
11	GPIO04	Ю	GPIO4, SSI_CLK, PWM4, SPI1_IO1, DFT_JTAG_TMS, JTAG_ENABLE			
12	GPIO00	0	GPIO00, PWM0, SPI1_CSN, JTAG_TDI			
13	GND	PWR	power ground			
14	TXD1	0	UART1_TXD, GPIO15, I2C1_SDA			
15	RXD1	Ю	UART1_RXD, GPIO16, I2C1_SCL			
16	GPIO12	0	GPIO12, PWM4, I2S_DI, ADC5			
17	GPIO14	Ю	GPIO14, DFT_JTAG_TRSTN, UART1_RTS			
18	GPIO01	Ю	GPIO01, PWM1, SPI1_IO0, JTAG_MODE			
19	GPIO08	Ю	GPIO08, PWM0, UART2_TXD, SPI0_CS1_N, ADC1			
20	GPIO10	Ю	GPIO10, PWM2, SPI0_CS0_N, I2S_SCLK, ADC3			
21	GPIO11	Ю	GPIO11, PWM3, SPI0_IN, I2S_LRCLK, ADC4			
22	GPIO09	Ю	GPIO09, PWM1, SPI0_OUT, I2S_DO, JTAG_TDO, ADC2			
23	NC		Not connected			
24	NC		Not connected			
25	GND	PWR	power ground			



	26	COME	PWR	Power supply, 5V
Ī	27	3V3	PWR	Power supply, 3.3V
	28	RST	IO	RESET signal of main chip



2.3 Dimensions

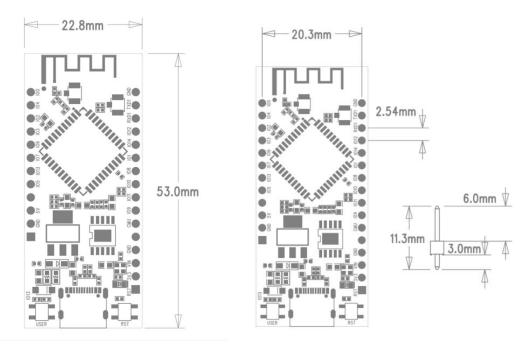


Figure 2-3 HH-D01 NearLink development board and pin header dimensions

2.4 Functional block diagram

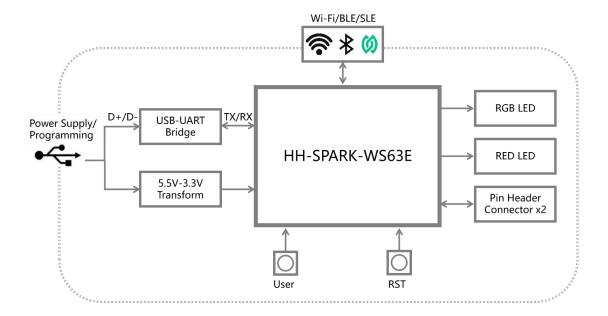


Figure 2-4 HH-D01 NearLink development board functional block diagram